

## PRELIMINARY DATASHEET

### IGBT Module in iQPak™2 Package PFC-Boost configuration

- Ultra low loss IGBT
- Highly rugged SPT design
- Pb free finished; RoHS compliant



**MAXIMUM RATINGS**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Units
Collector-emitter voltage	$V_{CES}$	1200	V
DC collector current $T_c=80^\circ\text{C}$	$I_C$	228	A
Repetitive peak collector current	$I_{CRM}$	456	
Diode DC forward current $T_c=80^\circ\text{C}$	$I_F$	200	
Peak forward current	$I_{FM}$	400	
Gate-emitter peak voltage	$V_{GES}$	$\pm 20$	V
IGBT short circuit SOA $V_{CC} = 1200\text{V}$ , $V_{GE} = 15\text{V}$ , $V_{CEM} \leq 1200\text{V}$ , $T_{VJ} \leq 125^\circ\text{C}$	$t_{SC}$	10	$\mu\text{s}$
Operating junction and storage temperature	$T_j, T_{stg}$	-40... +150	$^\circ\text{C}$

### Thermal and Isolation Characteristics

Parameter	Symbol	Max. Value	Units
<b>Characteristics</b>			
IGBT thermal resistance, junction to case	$R_{thJC}$	0.11	K/W
Diode thermal resistance, junction to case	$R_{thJCD}$	0.16	
Isolation voltage, RMS (measured between terminals and mounting base, 50-60 Hz, for 1-3 seconds)	$V_{iso}$	3000	V

**ELECTRICAL CHARACTERISTICS**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{V}$ , $I_C = 4\text{mA}$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(\text{sat})}$	$V_{GE} = 15\text{V}$ , $I_C = 228\text{A}$ $V_{GE} = 15\text{V}$ , $I_C = 200\text{A}$	1.7	1.87	2.0	
Diode forward voltage	$V_F$	$V_{GE} = 0\text{V}$ , $I_F = 200\text{A}$	-	1.8	2.2	
Gate-emitter threshold voltage	$V_{GE(\text{th})}$	$I_C = 8\text{ mA}$ , $V_{CE} = V_{GE}$	5.0	6.3	7.0	
Zero gate voltage collector current	$I_{CES}$	$V_{CE} = 1200\text{V}$ , $V_{GE} = 0$ $T = 25^\circ\text{C}$	-	-	400	
Gate-emitter leakage current	$I_{GES}$	$V_{CE} = 0\text{V}$ , $V_{GE} = \pm 20\text{V}$ ,	-200	-	200	
Internal gate resistance	$R_{Gint}$		-	2.5	-	$\Omega$

**ELECTRICAL CHARACTERISTICS**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

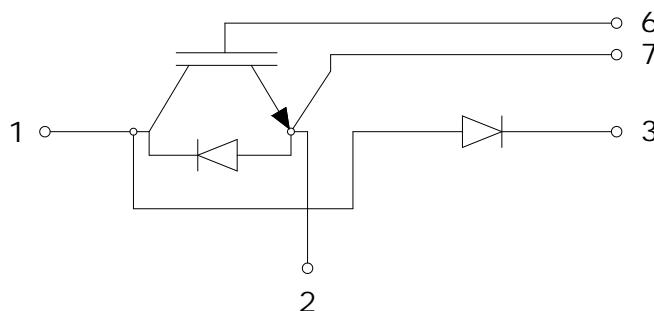
Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Dynamic Characteristics</b>						
Gate charge	$Q_{ge}$	$I_C = 228\text{A}, V_{CE} = 600\text{V}, V_{GE} = +15\text{V}$	-	2444	-	nC
Input capacitance	$C_{iss}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	17.2	-	nF
Reverse transfer capacitance	$C_{rss}$		-	1.2	-	
Reverse transfer capacitance	$C_{rss}$		-	0.8	-	
Short circuit current	$I_{sc}$	$T_C = 125^\circ\text{C}, V_{CC} = 900\text{V}, V_{GE} = 15\text{V}, t_{psc} \leq 10\mu\text{s}, V_{CEM} \leq 1200\text{V}$	-	1080	-	A

**SWITCHING CHARACTERISTICS**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

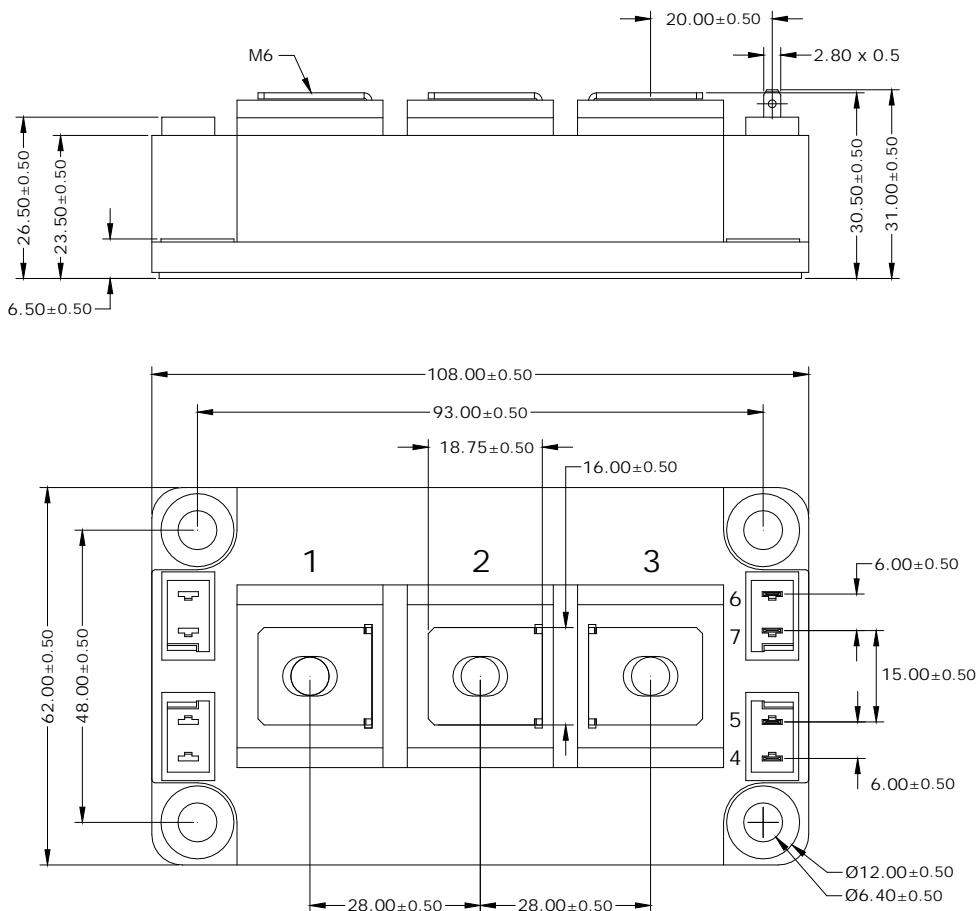
Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>IGBT Characteristics</b>						
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 600\text{V}, I_C = 228\text{A}, V_{GE} = -15\text{V to } 18\text{V}, R_G = 4.5\Omega, \text{Inductive load.}$	-	333	-	ns
Rise time	$t_r$		-	140	-	
Turn-off delay time	$t_{d(off)}$		-	224	-	
Fall time	$t_f$		-	115	-	
Turn-ON energy	$E_{on}$		-	46	-	mJ
Turn-OFF energy	$E_{off}$		-	13	-	mJ

**Anti-Parallel Diode Characteristics**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

Diode reverse recovery time	$t_{rr}$	$V_R = 600\text{V}, I_F = 200\text{A}, dI_F/dt = 650\text{A}/\mu\text{s}$ Inductive load	-	618	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	23	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	57	-	A



### Package Outline Drawing



CAUTION: These devices are ESD sensitive. Use proper handling procedure.

### Disclaimer

These specifications may not be considered as a guarantee of components characteristics. Components have to be tested depending on intended application as adjustments may be necessary. The use of **iQXPRZ Power Inc.** components in life support appliances and systems are subject to written approval of **iQXPRZ Power Inc.**